

## FEATURES

- Member of the Texas Instruments Widebus™ Family
- EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process
- Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors
- ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 250 mA Per JESD 17
- Package Options Include Plastic 300-mil Shrink Small-Outline (DL) and Thin Shrink Small-Outline (DGG) Packages

## DESCRIPTION

This 16-bit registered transceiver is designed for 1.65-V to 3.6-V  $V_{CC}$  operation.

The SN74ALVCH16543 can be used as two 8-bit transceivers or one 16-bit transceiver. Separate latch-enable ( $\overline{LEAB}$  or  $\overline{LEBA}$ ) and output-enable ( $\overline{OEAB}$  or  $\overline{OEBA}$ ) inputs are provided for each register to permit independent control in either direction of data flow.

The A-to-B enable ( $\overline{CEAB}$ ) input must be low to enter data from A or to output data from B. If  $\overline{CEAB}$  is low and  $\overline{LEAB}$  is low, the A-to-B latches are transparent; a subsequent low-to-high transition of  $\overline{LEAB}$  puts the A latches in the storage mode. With  $\overline{CEAB}$  and  $\overline{OEAB}$  both low, the 3-state B outputs are active and reflect the data present at the output of the A latches. Data flow from B to A is similar, but requires using  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$ .

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74ALVCH16543 is characterized for operation from -40°C to 85°C.

DGG OR DL PACKAGE  
(TOP VIEW)

$1\overline{OEAB}$	1	56	$1\overline{OEBA}$
$1\overline{LEAB}$	2	55	$1\overline{LEBA}$
$1\overline{CEAB}$	3	54	$1\overline{CEBA}$
GND	4	53	GND
1A1	5	52	1B1
1A2	6	51	1B2
$V_{CC}$	7	50	$V_{CC}$
1A3	8	49	1B3
1A4	9	48	1B4
1A5	10	47	1B5
GND	11	46	GND
1A6	12	45	1B6
1A7	13	44	1B7
1A8	14	43	1B8
2A1	15	42	2B1
2A2	16	41	2B2
2A3	17	40	2B3
GND	18	39	GND
2A4	19	38	2B4
2A5	20	37	2B5
2A6	21	36	2B6
$V_{CC}$	22	35	$V_{CC}$
2A7	23	34	2B7
2A8	24	33	2B8
GND	25	32	GND
$2\overline{CEAB}$	26	31	$2\overline{CEBA}$
$2\overline{LEAB}$	27	30	$2\overline{LEBA}$
$2\overline{OEAB}$	28	29	$2\overline{OEBA}$



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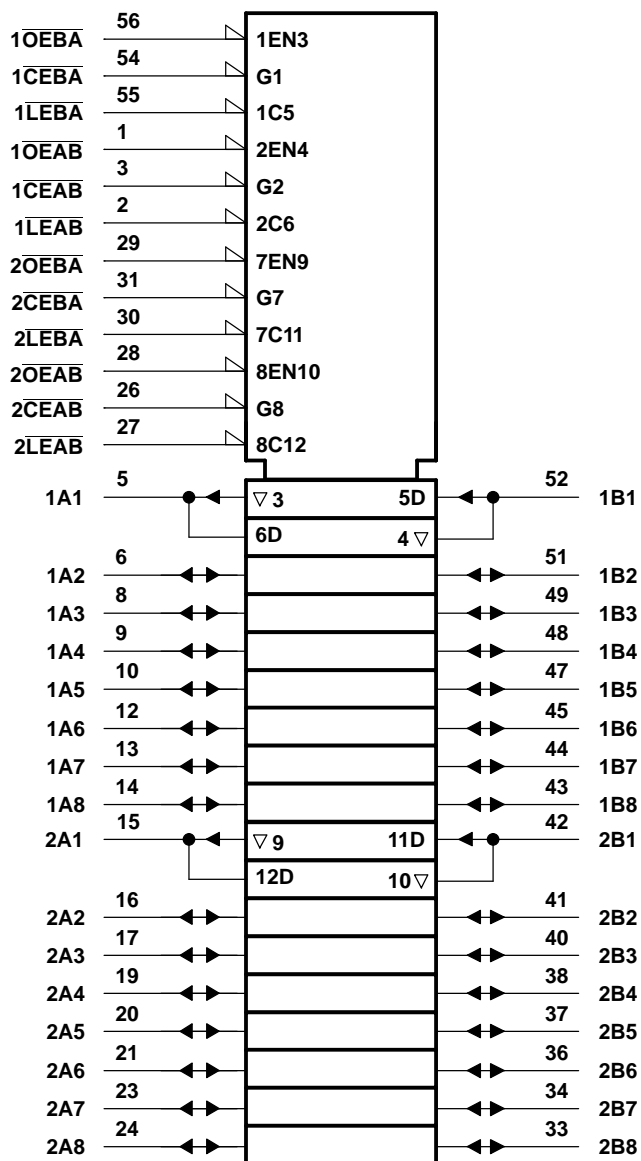
# SN74ALVCH16543

## 16-BIT REGISTERED TRANSCEIVER

### WITH 3-STATE OUTPUTS

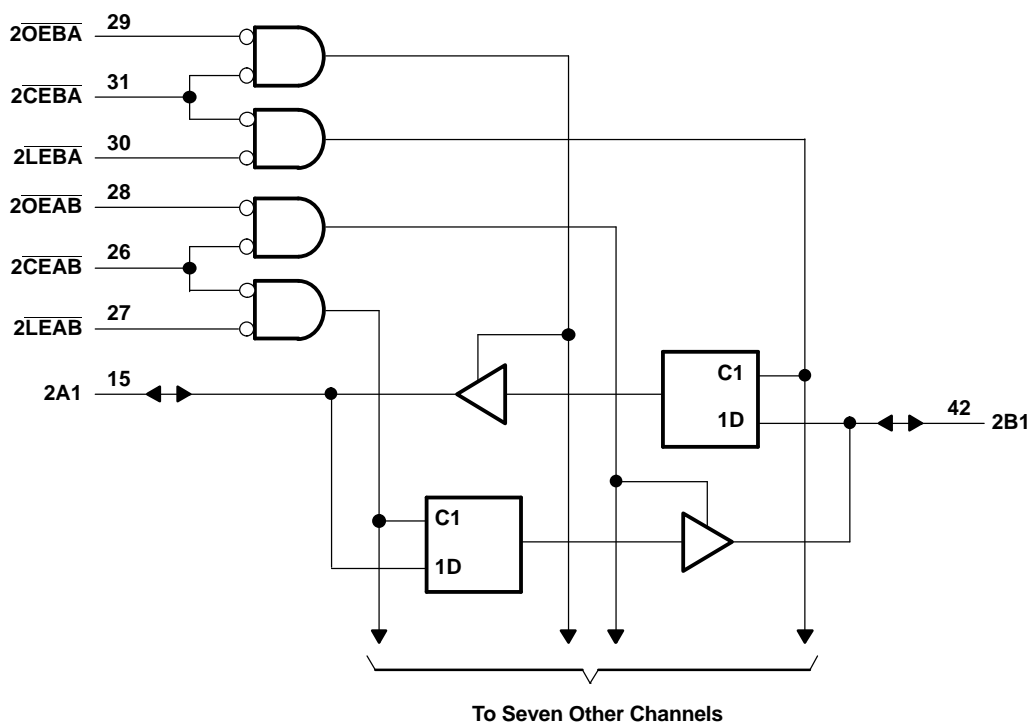
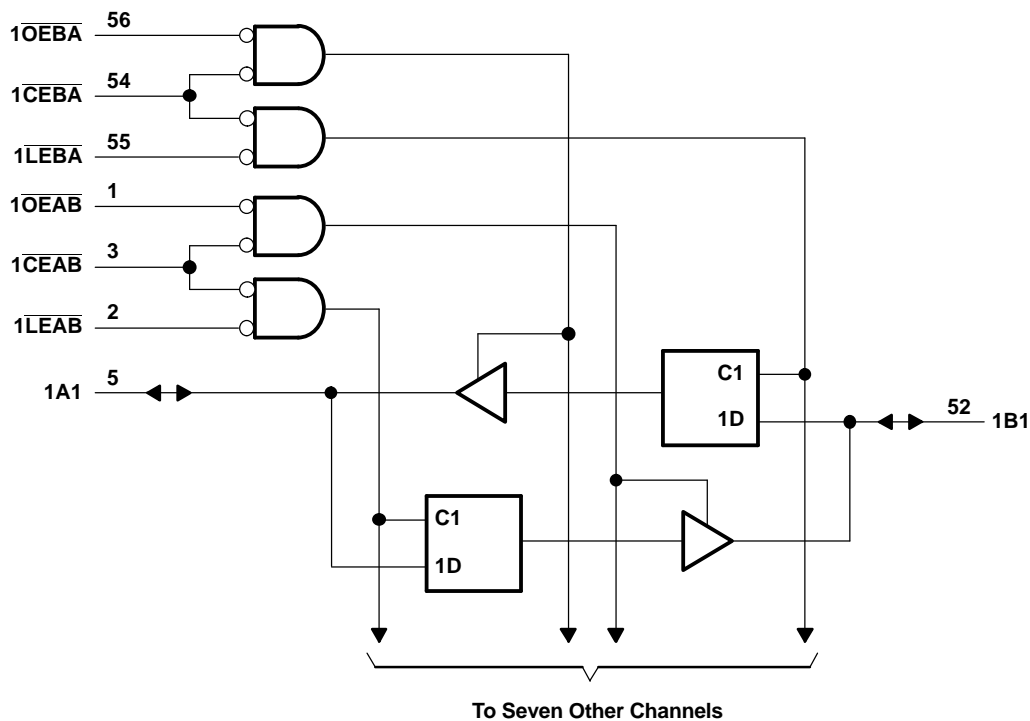
SCES025E—JULY 1995—REVISED OCTOBER 2004

LOGIC SYMBOL <sup>(1)</sup>



(1) This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

**LOGIC DIAGRAM (POSITIVE LOGIC)**



# SN74ALVCH16543

## 16-BIT REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS

SCES025E—JULY 1995—REVISED OCTOBER 2004

**FUNCTION TABLE<sup>(1)</sup>**  
**(each 8-bit section)**

INPUTS				OUTPUT B
$\overline{CEAB}$	$\overline{LEAB}$	$\overline{OEAB}$	A	
H	X	X	X	Z
X	X	H	X	Z
L	H	L	X	B <sub>0</sub> <sup>(2)</sup>
L	L	L	L	L
L	L	L	H	H

- (1) A-to-B data flow is shown; B-to-A flow control is the same, except that it uses  $\overline{CEBA}$ ,  $\overline{LEBA}$ , and  $\overline{OEBA}$ .
- (2) Output level before the indicated steady-state input conditions were established

### ABSOLUTE MAXIMUM RATINGS<sup>(1)</sup>

over operating free-air temperature range (unless otherwise noted)

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage range		-0.5	4.6	V
$V_I$	Input voltage range	Except I/O ports <sup>(2)</sup>	-0.5	4.6	V
		I/O ports <sup>(2) (3)</sup>	-0.5	$V_{CC} + 0.5$	
$V_O$	Output voltage range <sup>(2) (3)</sup>		-0.5	$V_{CC} + 0.5$	V
$I_{IK}$	Input clamp current	$V_I < 0$		-50	mA
$I_{OK}$	Output clamp current	$V_O < 0$		-50	mA
$I_O$	Continuous output current			±50	mA
	Continuous current through each $V_{CC}$ or GND			±100	mA
$\theta_{JA}$	Package thermal impedance <sup>(4)</sup>	DGG package		81	°C/W
		DL package		74	
$T_{stg}$	Storage temperature range		-65	150	°C

- (1) Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.
- (2) The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.
- (3) This value is limited to 4.6 V maximum.
- (4) The package thermal impedance is calculated in accordance with JESD 51.

## RECOMMENDED OPERATING CONDITIONS<sup>(1)</sup>

			MIN	MAX	UNIT
$V_{CC}$	Supply voltage		1.65	3.6	V
$V_{IH}$	High-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$	$0.65 \times V_{CC}$		V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$	1.7		
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$	2		
$V_{IL}$	Low-level input voltage	$V_{CC} = 1.65\text{ V to }1.95\text{ V}$		$0.35 \times V_{CC}$	V
		$V_{CC} = 2.3\text{ V to }2.7\text{ V}$		0.7	
		$V_{CC} = 2.7\text{ V to }3.6\text{ V}$		0.8	
$V_I$	Input voltage		0	$V_{CC}$	V
$V_O$	Output voltage		0	$V_{CC}$	V
$I_{OH}$	High-level output current	$V_{CC} = 1.65\text{ V}$		-4	mA
		$V_{CC} = 2.3\text{ V}$		-12	
		$V_{CC} = 2.7\text{ V}$		-12	
		$V_{CC} = 3\text{ V}$		-24	
$I_{OL}$	Low-level output current	$V_{CC} = 1.65\text{ V}$		4	mA
		$V_{CC} = 2.3\text{ V}$		12	
		$V_{CC} = 2.7\text{ V}$		12	
		$V_{CC} = 3\text{ V}$		24	
$\Delta t/\Delta v$	Input transition rise or fall rate			10	ns/V
$T_A$	Operating free-air temperature		-40	85	°C

- (1) All unused control inputs of the device must be held at  $V_{CC}$  or GND to ensure proper device operation. Refer to the TI application report, *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

# SN74ALVCH16543

## 16-BIT REGISTERED TRANSCEIVER WITH 3-STATE OUTPUTS

SCES025E–JULY 1995–REVISED OCTOBER 2004

### ELECTRICAL CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER		TEST CONDITIONS	V <sub>CC</sub>	MIN	TYP <sup>(1)</sup>	MAX	UNIT
V <sub>OH</sub>		I <sub>OH</sub> = -100 μA	1.65 V to 3.6 V	V <sub>CC</sub> - 0.2			V
		I <sub>OH</sub> = -4 mA	1.65 V	1.2			
		I <sub>OH</sub> = -6 mA	2.3 V	2			
	I <sub>OH</sub> = -12 mA	2.3 V	1.7				
		2.7 V	2.2				
		3 V	2.4				
		I <sub>OH</sub> = -24 mA	3 V	2			
V <sub>OL</sub>		I <sub>OL</sub> = 100 μA	1.65 V to 3.6 V	0.2		V	
		I <sub>OL</sub> = 4 mA	1.65 V	0.45			
		I <sub>OL</sub> = 6 mA	2.3 V	0.4			
	I <sub>OL</sub> = 12 mA	2.3 V	0.7				
		2.7 V	0.4				
		I <sub>OL</sub> = 24 mA	3 V	0.55			
I <sub>I</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND	3.6 V	±5		μA	
I <sub>I(hold)</sub>		V <sub>I</sub> = 0.58 V	1.65 V	25		μA	
		V <sub>I</sub> = 1.07 V	1.65 V	-25			
		V <sub>I</sub> = 0.7 V	2.3 V	45			
		V <sub>I</sub> = 1.7 V	2.3 V	-45			
		V <sub>I</sub> = 0.8 V	3 V	75			
		V <sub>I</sub> = 2 V	3 V	-75			
		V <sub>I</sub> = 0 to 3.6 V <sup>(2)</sup>	3.6 V	±500			
I <sub>OZ</sub> <sup>(3)</sup>		V <sub>O</sub> = V <sub>CC</sub> or GND	3.6 V	±10		μA	
I <sub>CC</sub>		V <sub>I</sub> = V <sub>CC</sub> or GND, I <sub>O</sub> = 0	3.6 V	40		μA	
ΔI <sub>CC</sub>		One input at V <sub>CC</sub> - 0.6 V, Other inputs at V <sub>CC</sub> or GND	3 V to 3.6 V	750		μA	
C <sub>i</sub>	Control inputs	V <sub>I</sub> = V <sub>CC</sub> or GND	3.3 V	3.5		pF	
C <sub>iO</sub>	A or B ports	V <sub>O</sub> = V <sub>CC</sub> or GND	3.3 V	8.5		pF	

(1) All typical values are at V<sub>CC</sub> = 3.3 V, T<sub>A</sub> = 25°C.

(2) This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

(3) For I/O ports, the parameter I<sub>OZ</sub> includes the input leakage current.

### TIMING REQUIREMENTS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

		V <sub>CC</sub> = 1.8 V		V <sub>CC</sub> = 2.5 V ± 0.2 V		V <sub>CC</sub> = 2.7 V		V <sub>CC</sub> = 3.3 V ± 0.3 V		UNIT
		MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>w</sub>	Pulse duration, $\overline{\text{LE}}$ or $\overline{\text{CE}}$ low	(1)		3.3		3.3		3.3		ns
t <sub>su</sub>	Setup time	Data before $\overline{\text{LE}}\uparrow$ or $\overline{\text{CE}}\uparrow$	(1)	1.2		1.5		1.2		ns
t <sub>h</sub>	Hold time	Data after $\overline{\text{LE}}\uparrow$ or $\overline{\text{CE}}\uparrow$	(1)	1.2		0.8		1.3		ns

(1) This information was not available at the time of publication.

## SWITCHING CHARACTERISTICS

over recommended operating free-air temperature range (unless otherwise noted) (see Figure 1 through Figure 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$ $\pm 0.2\text{ V}$		$V_{CC} = 2.7\text{ V}$		$V_{CC} = 3.3\text{ V}$ $\pm 0.3\text{ V}$		UNIT
			TYP	MIN	MAX	MIN	MAX	MIN	MAX	
$t_{pd}$	A or B	B or A	(1)	1	5.1	4.8		1	4.3	ns
	$\overline{LE}$	A or B	(1)	1	6.5	6.2		1.1	5	
$t_{en}$	$\overline{OE}$	A or B	(1)	1	7.2	6.9		1	5.6	ns
$t_{dis}$	$\overline{OE}$	A or B	(1)	1.3	6.1	6.2		1.5	5.1	ns
$t_{en}$	$\overline{OE}$	A or B	(1)	1	6.8	6.3		1	5.3	ns
$t_{dis}$	$\overline{OE}$	A or B	(1)	1	5.7	4.8		1.1	4.6	ns

(1) This information was not available at the time of publication.

## OPERATING CHARACTERISTICS

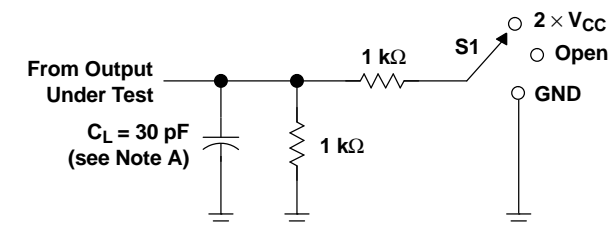
$T_A = 25^\circ\text{C}$

PARAMETER		TEST CONDITIONS	$V_{CC} = 1.8\text{ V}$	$V_{CC} = 2.5\text{ V}$	$V_{CC} = 3.3\text{ V}$	UNIT
			TYP	TYP	TYP	
$C_{pd}$	Power dissipation capacitance	Outputs enabled	(1)	54	64	pF
		Outputs disabled	(1)	6	7	

(1) This information was not available at the time of publication.

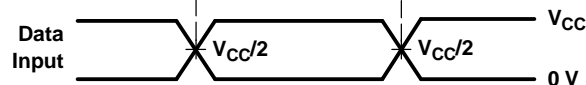
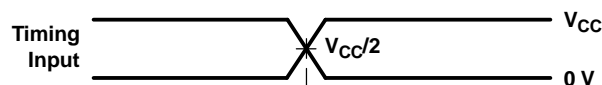
# PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 1.8 \text{ V}$$

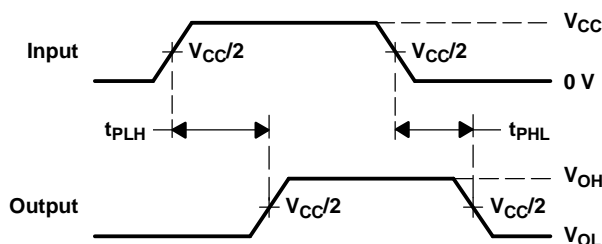


LOAD CIRCUIT

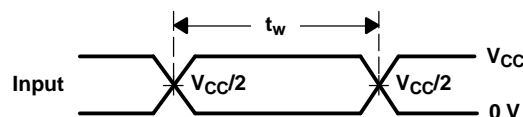
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZH}$	2 $\times V_{CC}$
$t_{PHZ}/t_{PHZ}$	GND



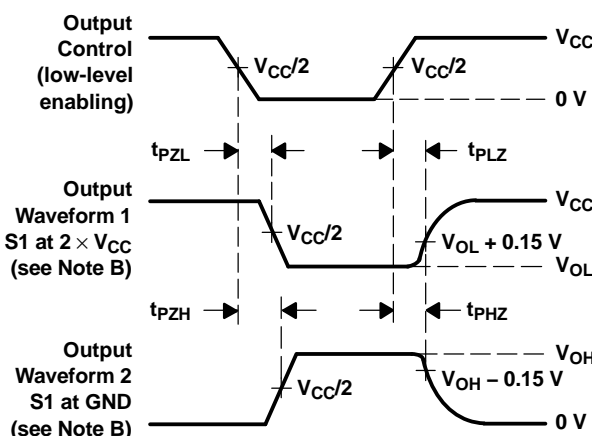
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

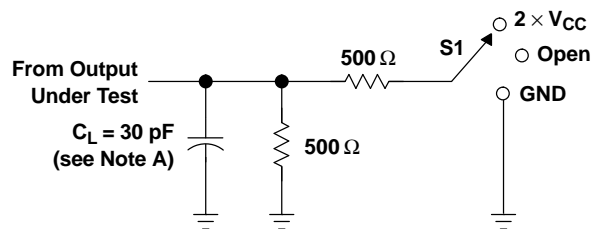
- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low, except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high, except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2 \text{ ns}$ ,  $t_f \leq 2 \text{ ns}$ .
  - The outputs are measured one at a time, with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms



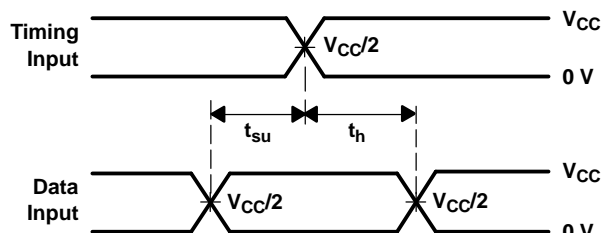
# PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.5 \text{ V} \pm 0.2 \text{ V}$$

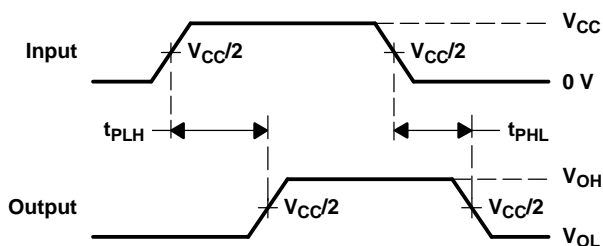


LOAD CIRCUIT

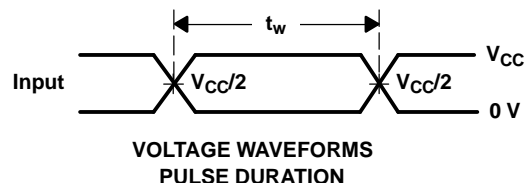
TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZH}$	$2 \times V_{CC}$
$t_{PHZ}/t_{PHZ}$	GND



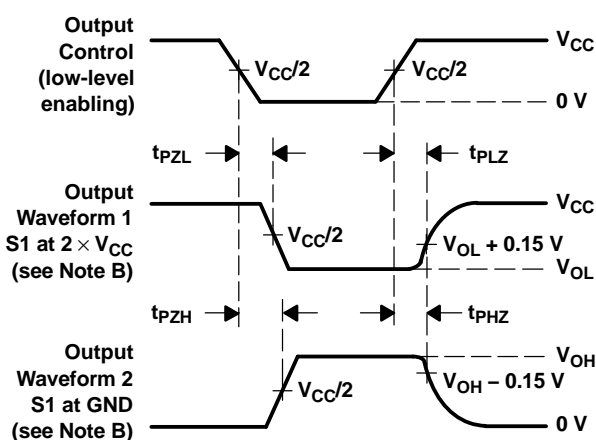
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



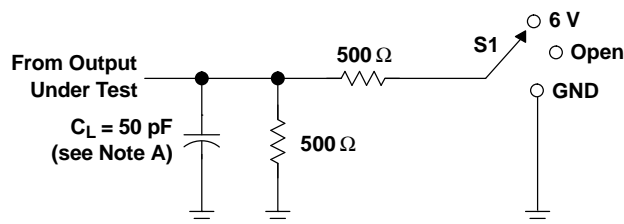
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ENABLE AND DISABLE TIMES

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  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 2. Load Circuit and Voltage Waveforms

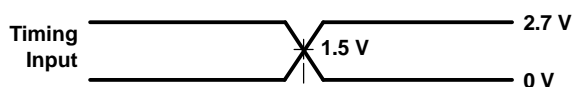
# PARAMETER MEASUREMENT INFORMATION

$$V_{CC} = 2.7 \text{ V AND } 3.3 \text{ V} \pm 0.3 \text{ V}$$

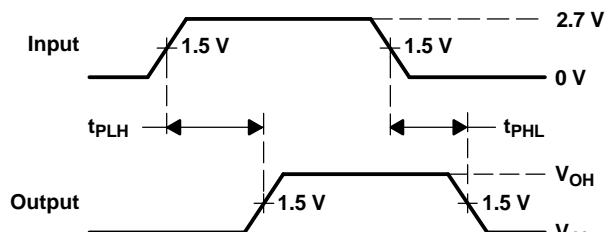


LOAD CIRCUIT

TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	6 V
$t_{PHZ}/t_{PZH}$	GND



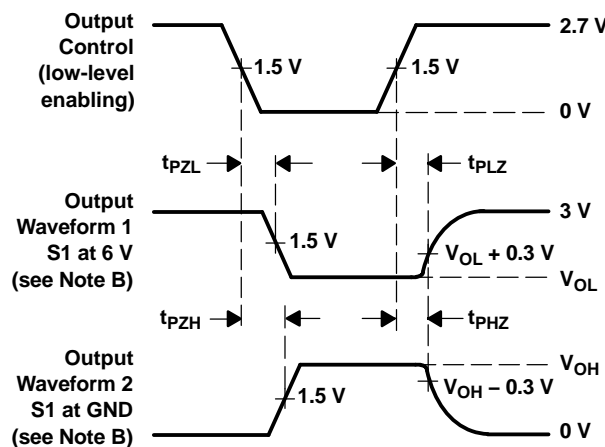
VOLTAGE WAVEFORMS  
SETUP AND HOLD TIMES



VOLTAGE WAVEFORMS  
PROPAGATION DELAY TIMES



VOLTAGE WAVEFORMS  
PULSE DURATION



VOLTAGE WAVEFORMS  
ENABLE AND DISABLE TIMES

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  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

**Figure 3. Load Circuit and Voltage Waveforms**

## PACKAGING INFORMATION

Orderable Device	Status <sup>(1)</sup>	Package Type	Package Drawing	Pins	Package Qty	Eco Plan <sup>(2)</sup>	Lead/Ball Finish	MSL Peak Temp <sup>(3)</sup>
74ALVCH16543DGGRE4	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16543DLG4	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
74ALVCH16543DLRG4	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16543DGGR	ACTIVE	TSSOP	DGG	56	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16543DL	ACTIVE	SSOP	DL	56	20	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN74ALVCH16543DLR	ACTIVE	SSOP	DL	56	1000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

<sup>(1)</sup> The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

<sup>(2)</sup> Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

<sup>(3)</sup> MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

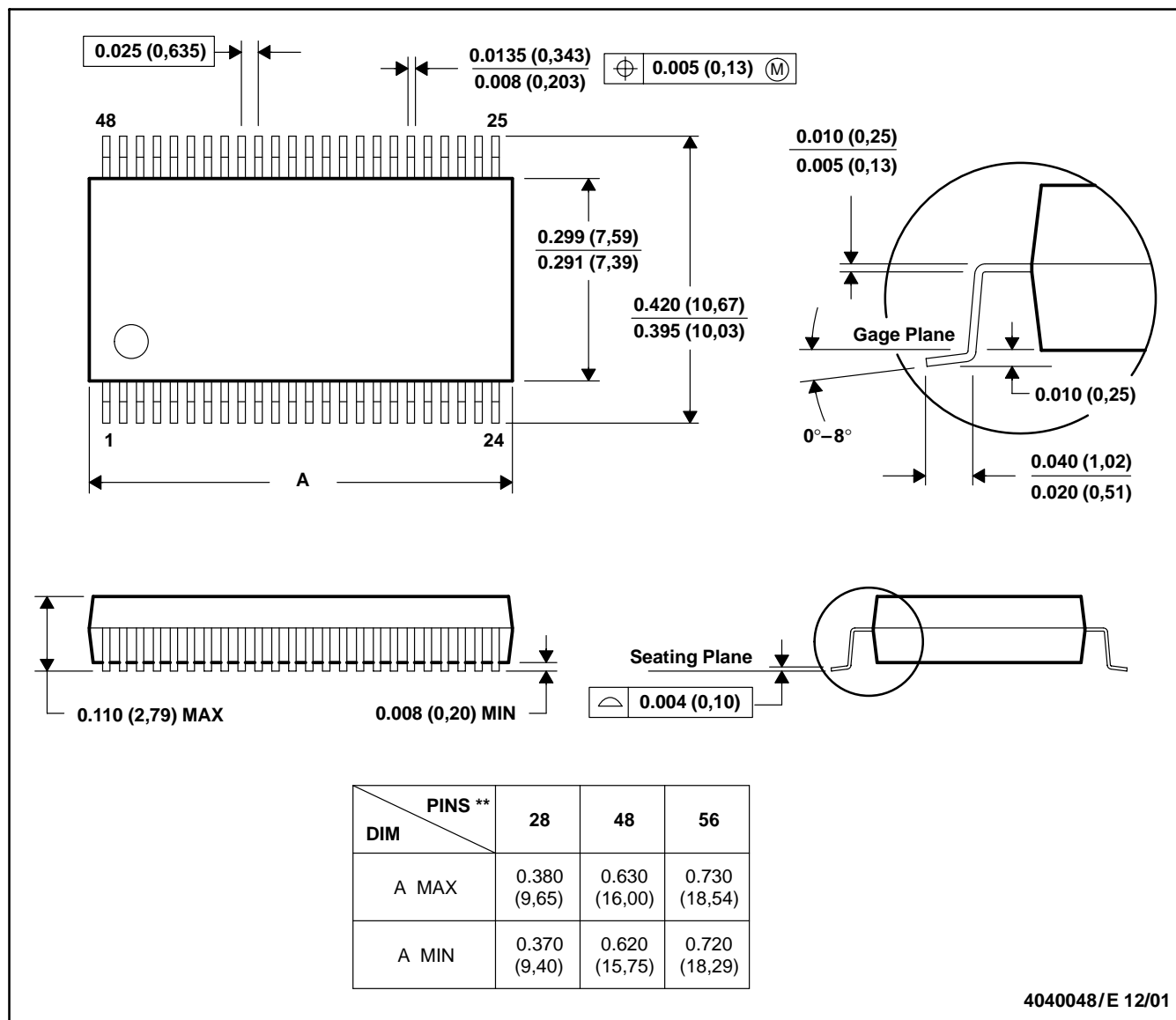
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## DL (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN

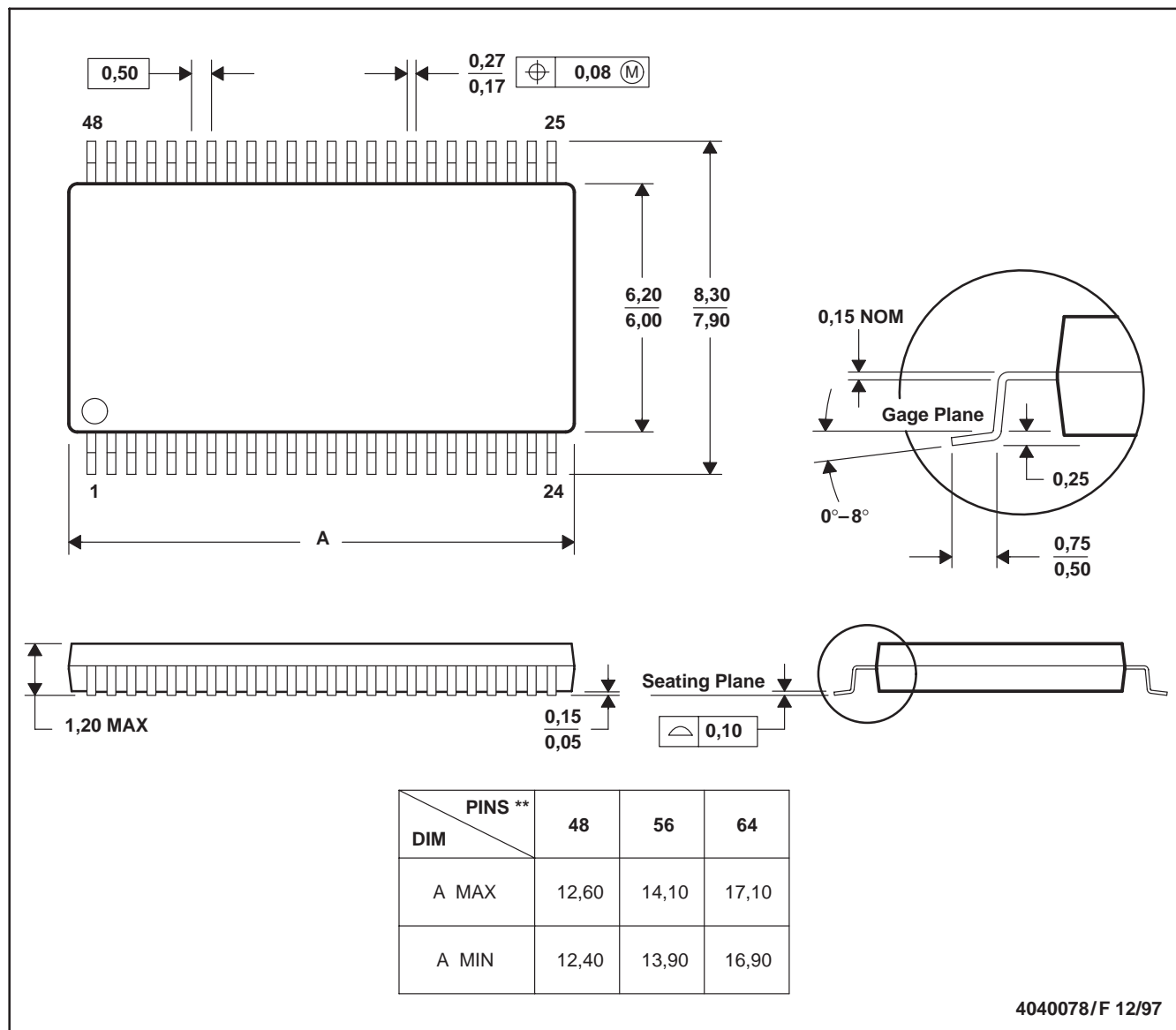


- NOTES: A. All linear dimensions are in inches (millimeters).  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).  
 D. Falls within JEDEC MO-118

## DGG (R-PDSO-G\*\*)

## PLASTIC SMALL-OUTLINE PACKAGE

48 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Body dimensions do not include mold protrusion not to exceed 0,15.  
 D. Falls within JEDEC MO-153

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